

L8550QLT1G

General Purpose Transistors PNP Silicon

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.

2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
L8550QLT1G	1YD	3000/Tape&Reel
L8550QLT3G	1YD	13000/Tape&Reel

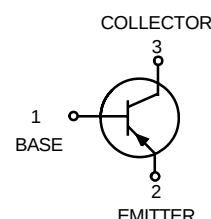
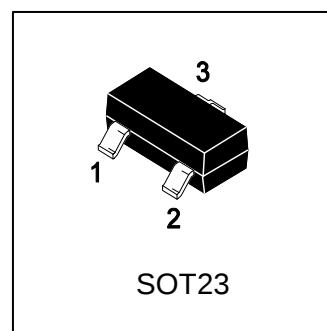
3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Collector-Emitter Voltage	VCEO	-25	V
Collector-Base voltage	VCBO	-40	V
Emitter-Base Voltage	VEBO	-5	V
Collector current-continuoun	IC	-800	mA
Junction temperature	TJ	-55 ~ +150	°C
Storage temperature	Tstg	-55 ~ +150	°C

4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	312 2.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	400	°C/W

1. 30.0mm×25.0mm×1.6mm(FR4), Copper foil thickness 35μm;



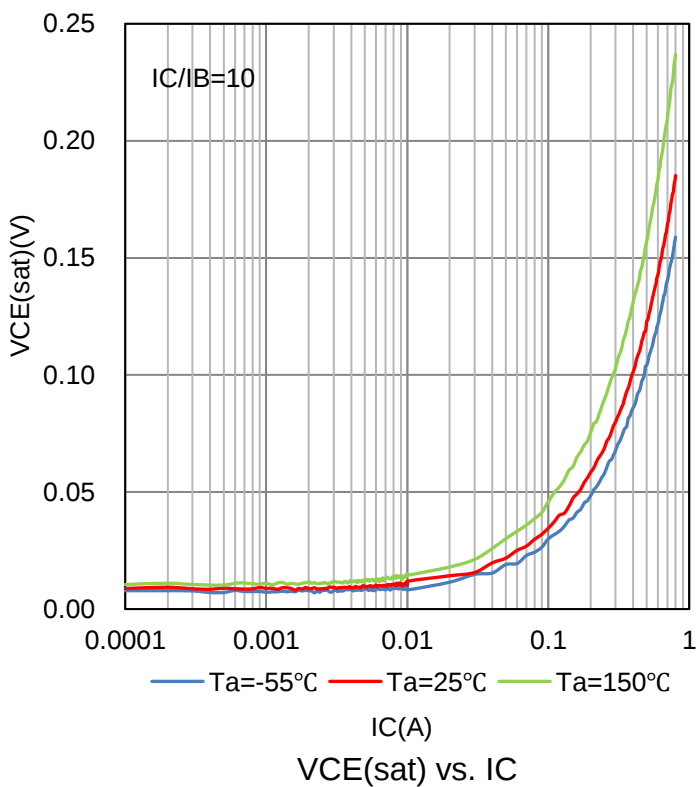
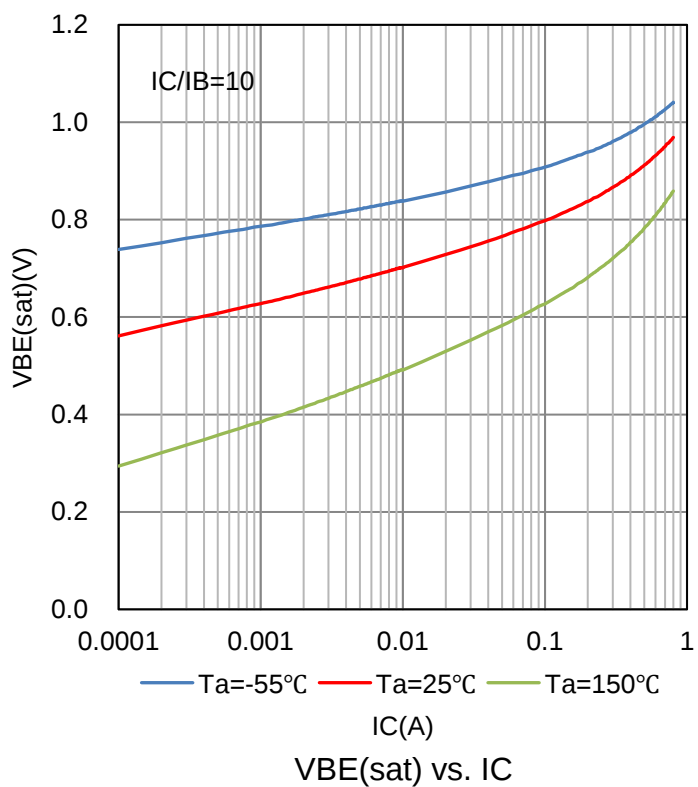
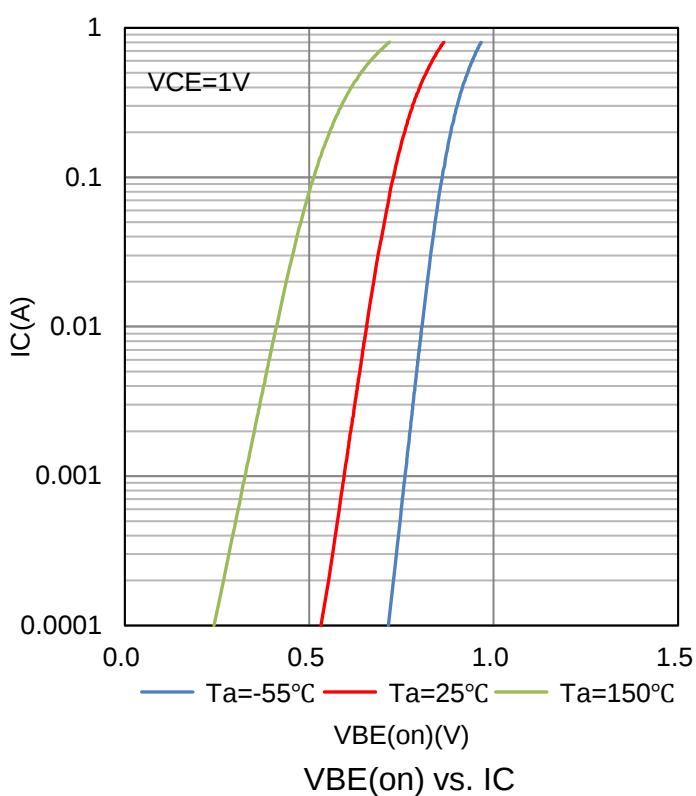
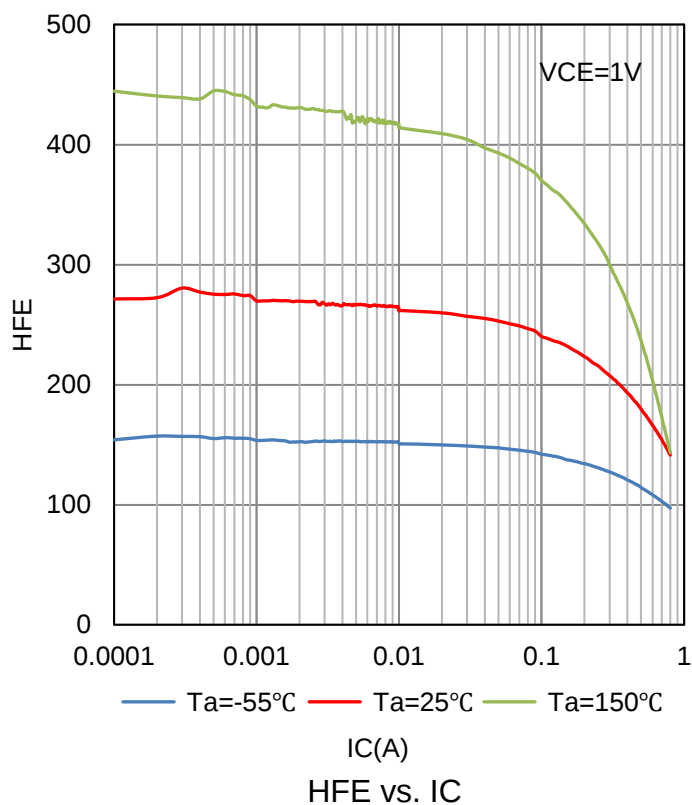
5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)**OFF CHARACTERISTICS**

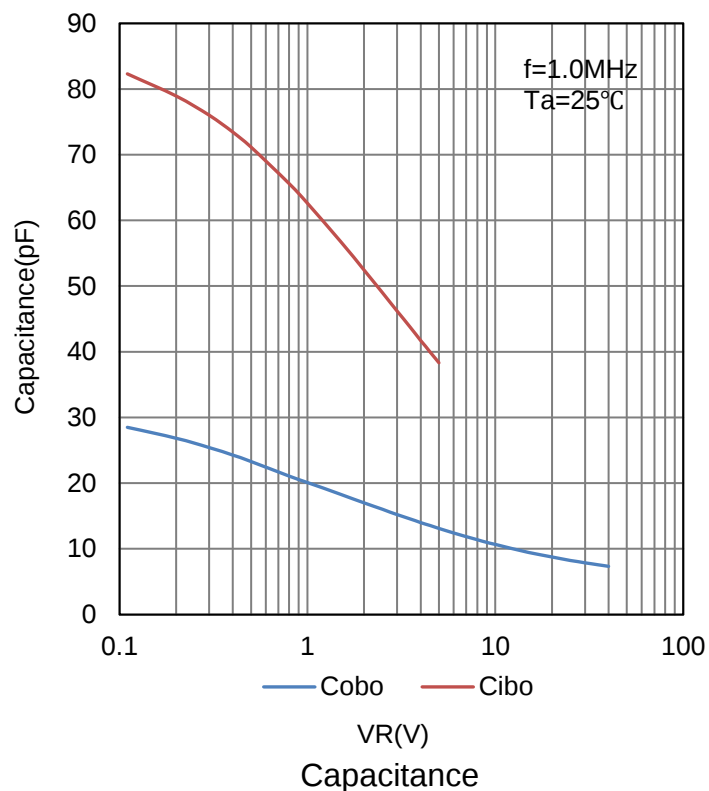
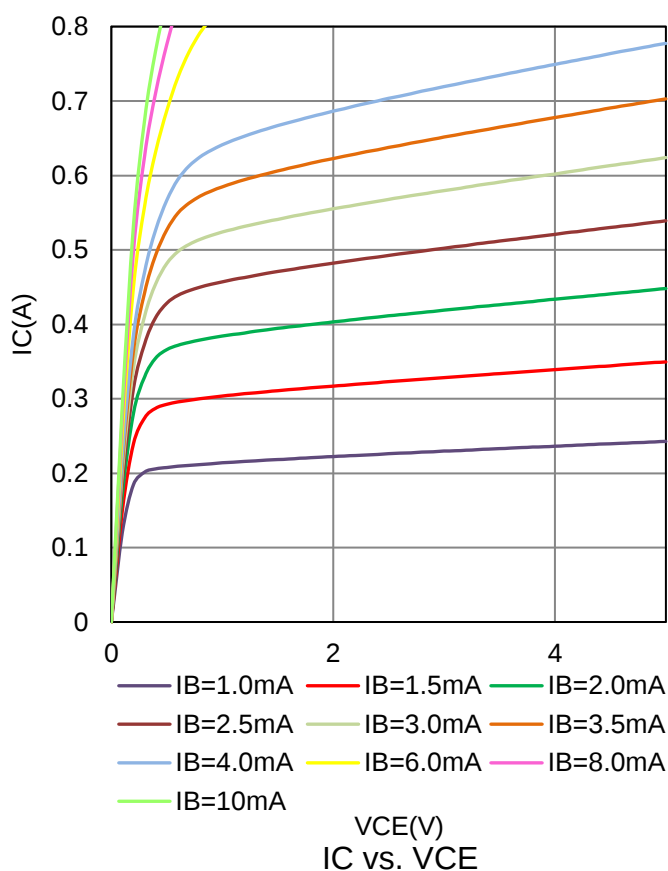
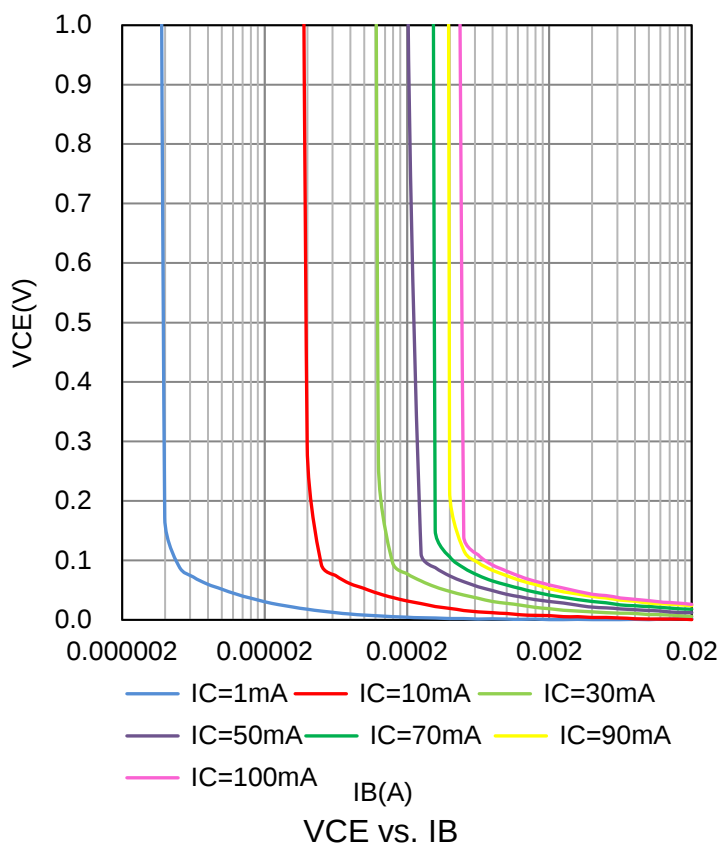
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Collector-Emitter Breakdown Voltage (IC = -1.0mA)	V(BR)CEO	-25	-	-	V
Emitter-Base Breakdown Voltage (IE = -100μA)	V(BR)EBO	-5	-	-	V
Collector-Base Breakdown voltage (IC = -100μA)	V(BR)CBO	-40	-	-	V
Collector Cutoff Current (VCB = -35 V)	ICBO	-	-	-150	nA
Emitter Cutoff Current (VEB = -4V)	IEBO	-	-	-150	nA
Emitter Cutoff Current (VCE = -20V, IB = 0)	ICEO	-	-	-10	μA

ON CHARACTERISTICS

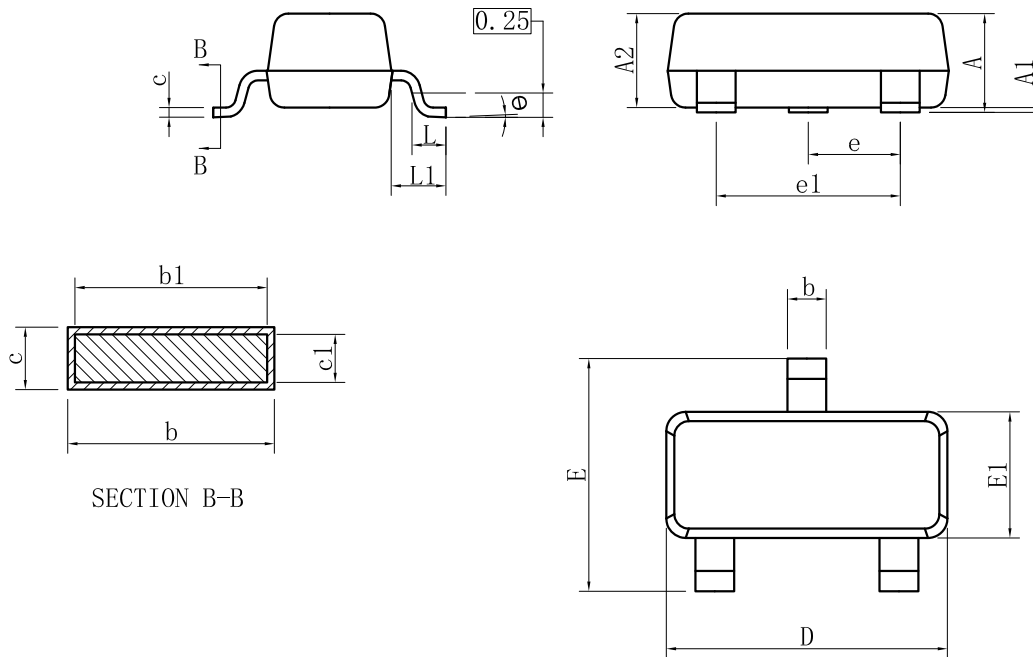
DC Current Gain (IC = -100mA, VCE = -1V)	HFE	150	-	300	
Collector-Emitter Saturation Voltage (IC = -800mA, IB = -80mA)	VCE(S)	-	-	-0.5	V

6.ELECTRICAL CHARACTERISTICS CURVES



6.ELECTRICAL CHARACTERISTICS CURVES(Con.)


7.OUTLINE AND DIMENSIONS

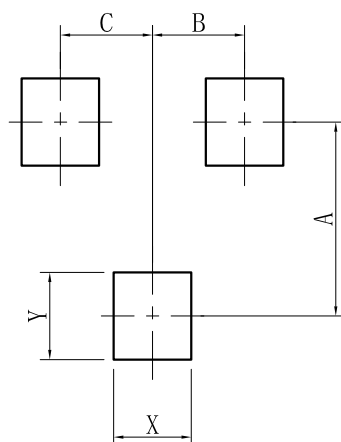


SOT23			
DIM	MIN	NOR	MAX
A	0.89	-	1.12
A1	0.01	-	0.10
A2	0.88	0.95	1.02
b	0.30	-	0.50
b1	0.30	0.40	0.45
c	0.08	-	0.20
c1	0.08	0.10	0.16
D	2.80	2.90	3.04
E	2.10	-	2.64
E1	1.20	1.30	1.40
e	0.95BSC		
e1	1.90BSC		
L	0.40	0.46	0.60
L1	0.54REF		
θ	0°	-	8°
All Dimensions in mm			

GENERAL NOTES

- 1.Top package surface finish Ra0.4±0.2um
- 2.Bottom package surface finish Ra0.7±0.2um
- 3.Side package surface finish Ra0.4±0.2um

8.SOLDERING FOOTPRINT



SOT-23	
DIM	(mm)
X	0.80
Y	0.90
A	2.00
B	0.95
C	0.95

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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